

# LNJ824C43RA

## High Bright Surface Mounting Chip LED

3528 (PLCC2) Type

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	55	mW
Forward current	$I_F$	20	mA
Pulse forward current *	$I_{FP}$	60	mA
Reverse voltage	$V_R$	4	V
Operating ambient temperature	$T_{opr}$	-40 to +100	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +100	$^\circ\text{C}$

### ■ Lighting Color

- Orange

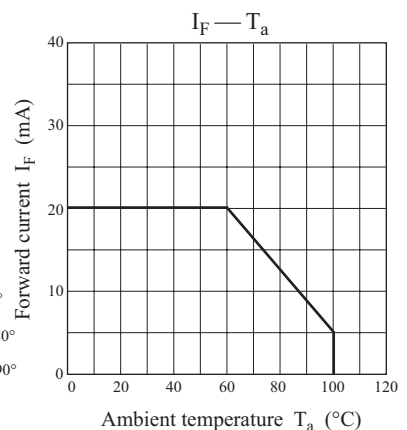
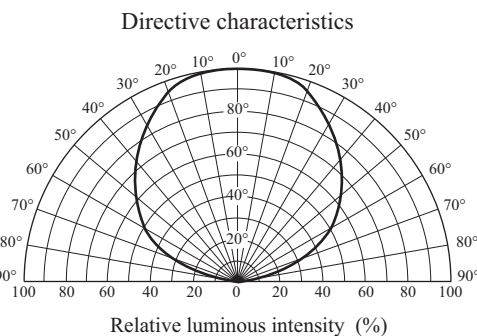
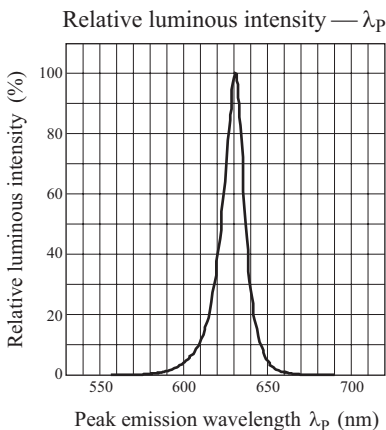
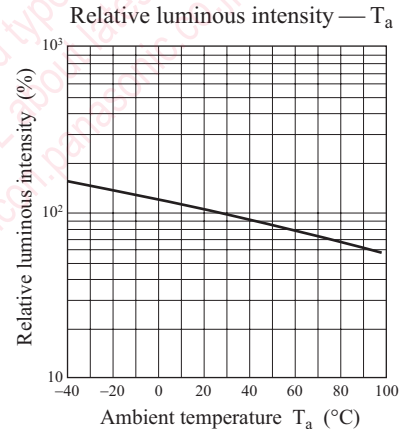
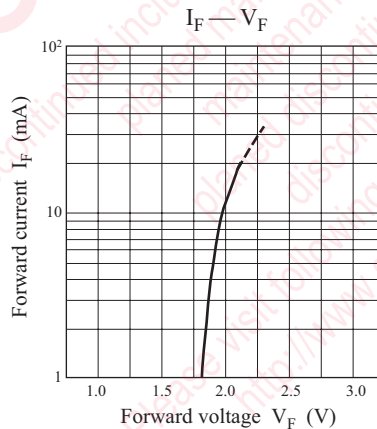
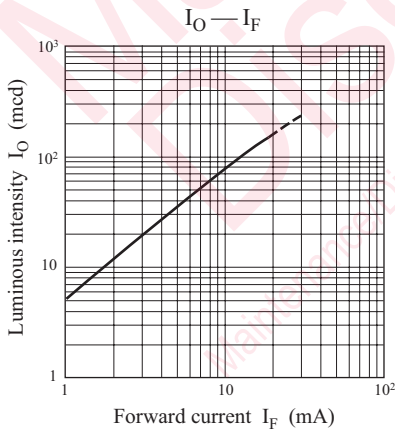
Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

### ■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *1	$I_O$	$I_F = 10 \text{ mA}$	50	80	120	mcd
Reverse current	$I_R$	$V_R = 4 \text{ V}$			100	$\mu\text{A}$
Forward voltage	$V_F$	$I_F = 10 \text{ mA}$		2.0	2.4	V
Peak emission wavelength	$\lambda_p$	$I_F = 10 \text{ mA}$		630		nm
Dominant emission wavelength *2	$\lambda_d$	$I_F = 10 \text{ mA}$	615	621	627	nm
Spectral half band width	$\Delta\lambda$	$I_F = 10 \text{ mA}$		20		nm

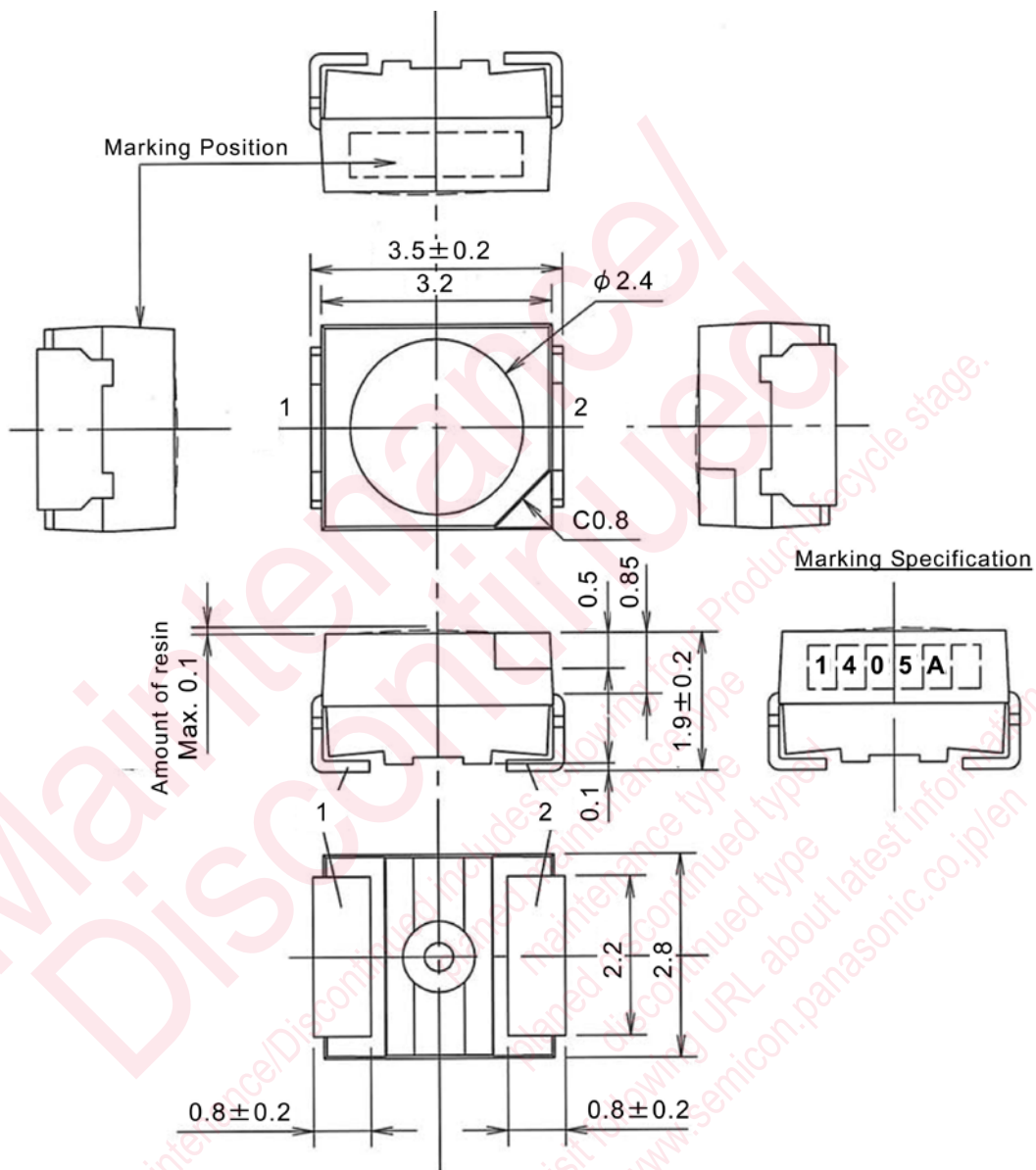
Note) \*1: Measurement tolerance:  $\pm 15\%$

\*2: Measurement tolerance:  $\pm 2 \text{ nm}$



■ Package (Unit: mm)

LLDFTR4J2400



- Pin name
- 1: Anode
- 2: Cathode

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